

## High Voltage PWM Controller

### General Description

AT6000Z is a highly integrated current mode PWM controller for flyback converter, optimized for high performance, low standby power consumption and cost effective offline flyback converter applications.

The AT6000Z built-in multiple protection with VCC under voltage lockout (UVLO), VCC over voltage protection (OVP), high voltage startup circuit, VCC clamp, GATE clamp, cycle-by-cycle current limiting (OCP), over load protection (OLP), and leading-edge blanking (LEB) of the current sensing to prevent circuit damage occurred under abnormal conditions.

The AT6000Z is available in an SOP-8L package and require very few external devices for operation.

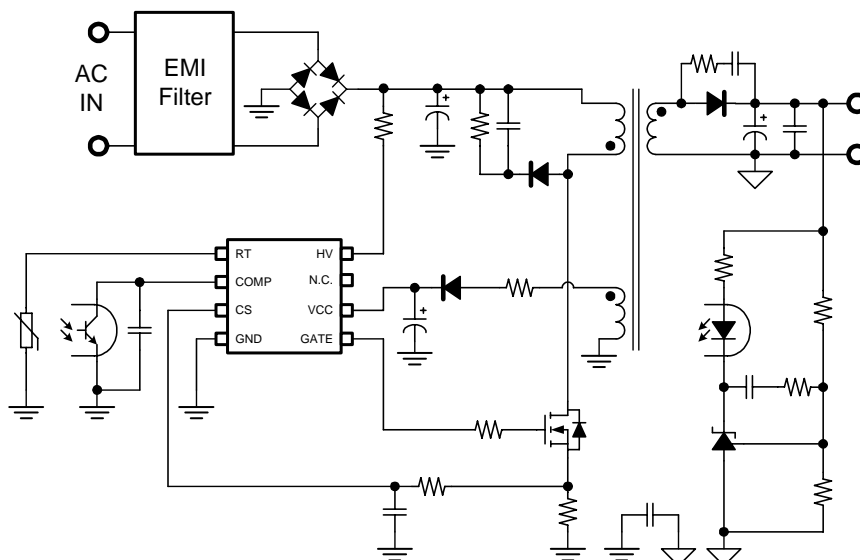
### Features

- High Voltage Startup Circuit
- VCC Under Voltage Lockout (UVLO)
- VCC Over voltage Protection (OVP)
- Cycle-by-Cycle Current Limiting (OCP)
- Over Load Protection (OLP)
- Connection of an NTC for Over Temperature Protection (OTP)
- Leading Edge Blanking (LEB)
- VCC & Gate Voltage Clamp
- 65kHz Switching Frequency
- 500mA Source/500mA Sink Gate Driver
- SOP-8 Package

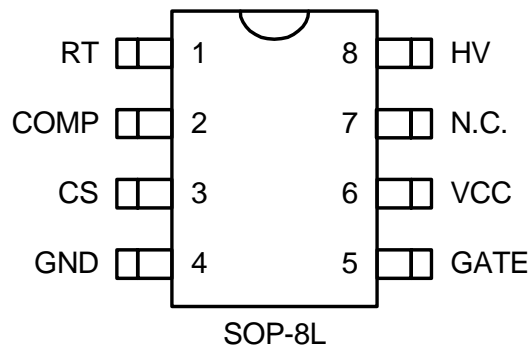
### Applications

- AC/DC Switching Power Adaptor
- Battery Charger
- Open Frame Switching Power Supply

### Typical Application Circuit



## Pin Configuration



## Function Pin Description

Pin No.	Pin Name	Description
1	RT	<b>Temperature Detection.</b> An internal current source allows the direct connection of an NTC for over temperature detection.
2	COMP	<b>Voltage Feedback.</b> This pin connecting an opto-coupler to monitor output for regulation control loop.
3	CS	<b>Current Sense.</b> This pin sense primary MOSFET current.
4	GND	<b>Ground.</b>
5	GATE	<b>PWM Signal Output.</b> This pin output to drive the external power MOSFET.
6	VCC	<b>Power Supply.</b>
7	N.C.	<b>No Connection.</b>
8	HV	<b>High Voltage.</b> This pin connects to bulk capacitor via resistors for controller high voltage start-up current source.

## Protection Mode

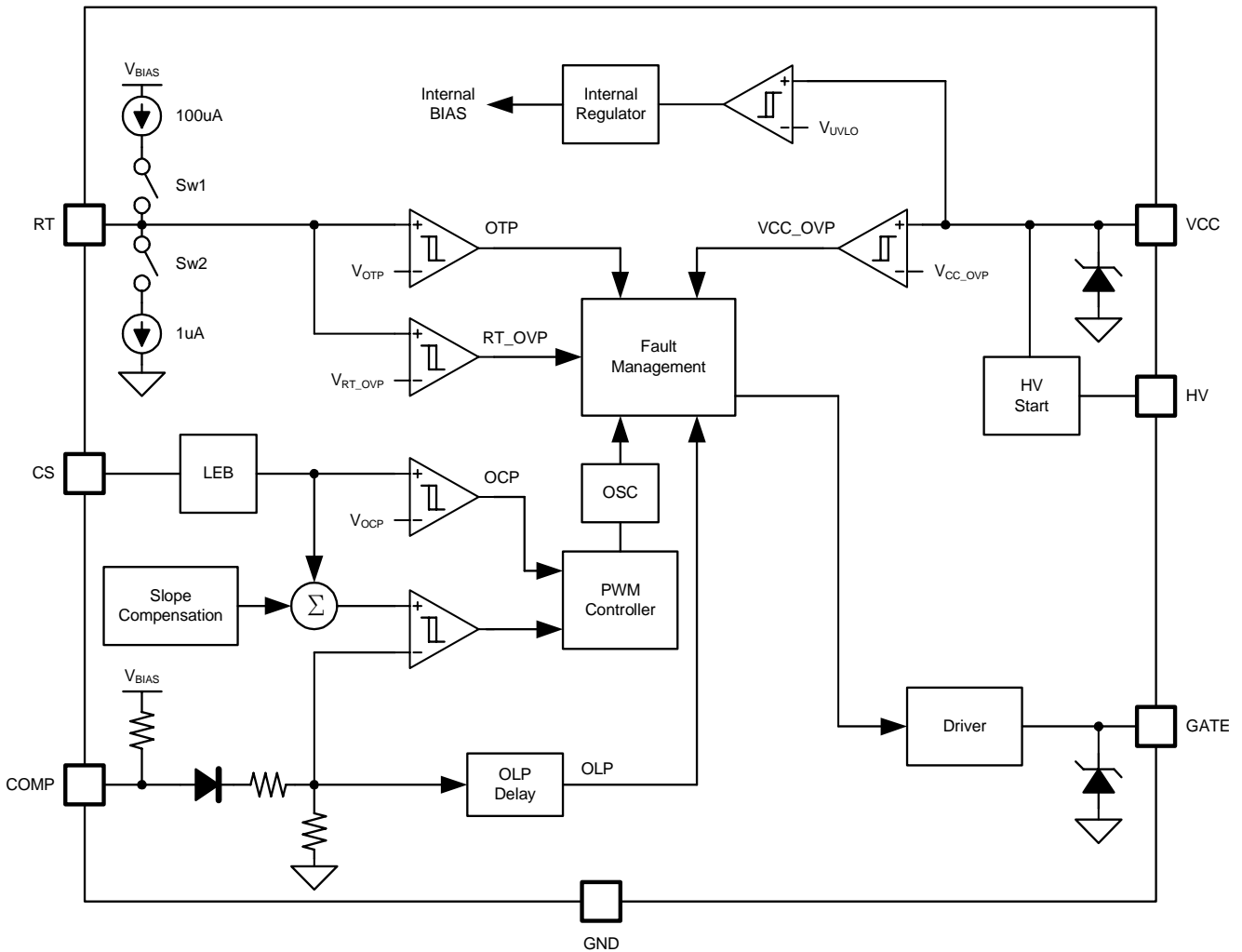
Part Number	Switching Frequency	OLP	VCC OVP	RTLTP	RTHP	Int. TSD
AT6000Z	65kHz	Auto	Latch	Latch	Latch	Auto

## Ordering and Marking Information

Order Number	Package	Top Marking
AT6000ZSP8	SOP-8L	AT6000Z

Note: Aplustek products are compatible with the current IPC/JEDEC J-STD-020 requirement. They are halogen-free, RoHS compliant and 100% matte tin (Sn) plating that are suitable for use in SnPb or Pb-free soldering processes.

## Function Blocks





**Absolute Maximum Ratings**

(Note1)

Supply Input Voltage, VCC	-----	-0.3V to +32V
High-Voltage Pin, HV	-----	- 0.3V to +600V
RT, COMP, CS	-----	-0.3V to +7V
GATE	-----	-0.3V to +20V
Storage Temperature Range	-----	-65°C to +150°C
Junction Temperature	-----	-40°C to +150°C
Lead Temperature Range(Soldering 10sec)	-----	260°C

ESD Rating (Note2)

HBM(Human Body Mode, Except HV Pin)	-----	4KV
HBM(Human Body Mode, HV Pin)	-----	1.5KV
MM(Mechine Mode)	-----	400V

**Thermal Characteristics**

Package Thermal Resistance (Note3)

SOP-8L $\theta_{JA}$	-----	250°C/W
SOP-8L $\theta_{JC}$	-----	140°C/W

Power Dissipation, PD @ TA = 25°C

SOP-8L	-----	400mW
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**Electrical Characteristics**

( V<sub>CC</sub> = 12V, T<sub>A</sub> = +25°C unless otherwise specified.)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
<b>Supply Input Section</b>						
Operating Voltage			8	--	27	V
Power On Voltage	VCC_on		13.5	14	14.5	V
Holdup Voltage	VCC_hold	IHV>1mA	8	8.5	9	V
Power Off Voltage	VCC_off		7	7.5	8	V
Reset Voltage	VCC_rst		6	6.5	7	V
Over Voltage Protection Voltage	VCC_ovp		27	28.5	30	V
Internal Zener Clamp	VCC_clamp	ICC>2*ICC_op	--	31	--	V
Startup Current	ICC_start		200	270	350	uA
Normal Operating Current	ICC_op	C <sub>L</sub> =1nF	--	1.3	--	mA
Burst Mode Operating Current	ICC_bs	VCMOP<VCMOP_bs	--	0.35	--	mA
<b>COMP Pin Section</b>						
COMP Pull High Impedance	ZCOMP		--	20	--	kΩ
Open Loop Voltage	VCOMP_o	COMP Open	--	5	--	V
Over Load Protection Voltage	VCOMP_olp		--	4.4	--	V
Over Load Protection Debounce Time	Tdeb_olp		--	65	--	ms



Parameter		Test Conditions	Min	Typ	Max	Units
<b>High Voltage Section</b>						
High-Voltage Current	IHV_on	VCC>1V	2.5	3	3.5	mA
Initial High-Voltage Current	IHV0_on	VCC=0V	--	0.67	--	mA
High-Voltage Off Current	IHV_off	VHV=600V,VCC>VCC_on	--	--	20	uA
<b>Oscillation Section</b>						
Nominal Frequency	Fosc_n	VCOMP>VCOMP_f	61	65	69	kHz
Green Frequency	Fosc_gr	VCOMP_bs<VCOMP<VCOMP_gr		24		kHz
COMP Threshold for Frequency Reduction	VCOMP_f	Fosc<Fosc_n	--	2.2	--	V
COMP Voltage for Green Frequency	VCOMP_gr	Fosc=Fosc_gr	--	2	--	V
COMP Threshold for Zero Duty	VCOMP_bs		--	1.6	--	V
Frequency Hopping Range		Fosc=Fosc_n	--	+5	--	%
<b>Current Sense Section</b>						
Delay to Output			--	--	100	ns
Leading Edge Blanking Time	t_leb	VCS>1.1V	--	350	--	ns
Minimum On Time	ton_min		--	710	--	ns
CS Threshold at Max Duty	VCS_max	Fosc=Fosc_n	0.885	0.9	0.915	V
Input Impedance	ZCS		1	--	--	MΩ
Soft Start Time	tss		--	0.5	--	ms
<b>GATE Section</b>						
Maximum Duty Cycle	Dmax	Max Frequency	71	80	89	%
Output Voltage Low	Vol	VCC=15V, I <sub>o</sub> =20mA Sinking	--	0.12	0.25	V
Output Voltage High	Voh	VCC=15V, I <sub>o</sub> =20mA Sourcing	9	11	--	V
Rising Time	tr	CL=1nF,Vgate from 2V to 6V	--	88	--	ns
Falling Time	tf	CL=1nF,Vgate from 6V to 2V	--	10	--	ns
Gate Voltage Clamping	Vgate_clamp	VCC=27V	12	14	16	V
<b>RT Pin Section</b>						
Floating Voltage of RT	VRT_o	RT Open	2.1	2.3	2.5	V
RT Sourcing Current	IRT	RT < 1.5V	95	100	105	uA
RT High Level Protection	VRTTHP		3.325	3.5	3.675	V
RT Low Level Protection	VRTTLP		0.95	1	1.05	V
RT Low Protection Blanking Time after Power On	tbk_rtlp		--	5.12	--	ms
<b>TSD Section</b>						
Internal Thermal Protection	TSD_int		--	140	--	°C



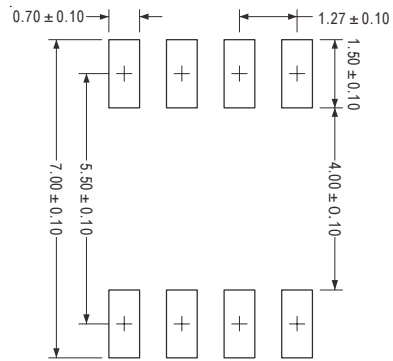
Parameter		Test Conditions	Min	Typ	Max	Units
<b>Fault Section</b>						
Fault Recycle Time	tcyc_fault		--	1	--	s
Fault Debounce Time (Exclude OLP)	tdeb_fault		--	75	--	us

**Note 1.** Exceeding these limits may impair the life of the device. Exposure to absolute maximum rating conditions for long periods may affect device reliability.

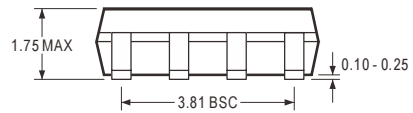
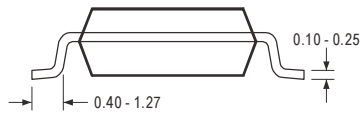
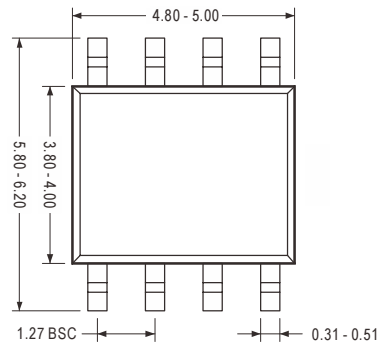
**Note 2.**  $\theta_{JA}$  is measured with the component mounted on a high effective thermal conductivity test board in free air. The exposed pad of the package is soldered directly on the PCB.

## Package Information

### SOP-8L



Recommended Solder Pad Layout



#### Note

##### 1. Package Outline Unit Description:

BSC: Basic. Represents theoretical exact dimension .

MAX: Maximum dimension specified.

MIN: Minimum dimension specified.

REF: Represents dimension for reference use only. The value is not the device specification.

TYP: Represents as a typical value. The value is not the device specification.

##### 2. All linear dimensions are in Millimeters.